

## **Final Product Change Notification**

Issue Date:07-Dec-2014Effective Date:07-Mar-2015

WITHDRAWAL

## 201402008F01W

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# QUALITY

#### **Management Summary**

Please be informed that this is a Withdrawal PCN.

Original PCN Summary - Bipolar PL has modernised our ACT chip design in line with our up-to-date technology platform for ACT108(W)-600E.

#### Change Category

[] Wafer Fab process [] Wafer Fab materials [] Wafer Fab location

[] Assembly Materials [] Assembly Location

[X] Assembly Process

[] Product Marking

[] Electrical spec./Test coverage

[X] Design [] Mechanical Specification [] Packing/Shipping/Labeling

New Crystal Design (platform) and increasing one bonding wire for ACT108(W)-600E

[] Test Location

#### Details of this Change

Please be informed that this is a Withdrawal PCN.

Original PCN content - Bipolar PL has modernised our ACT chip design in line with our up-to-date technology platform. We have also taken the opportunity while introducing this improved chip to standardise wirebonding to 4 bonding wires (from the previous 3), in line with current assembly capabilities. These two enhancements lead to improved electrical performance for the end product.

Why do we Implement this Change It is to upgrade the electrical performance. Identification of Affected Products Diffusion Record

### **Product Availability**

Sample Information Samples are available upon request Production Planned first shipment 26-May-2014

Withdrawal Information

Due to internal logistic and operation management, ACT108(W)-600E with original crystal will remain unchanged. The modernized chip is available as a new product ACT108(W)-800E.

Impact

no impact to the product's functionality anticipated.

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

**Timing and Logistics** 

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 06-Jan-2015.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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 Customer Focus, Passion to Win.

NXP Quality Management Team. About NXP Semiconductors

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